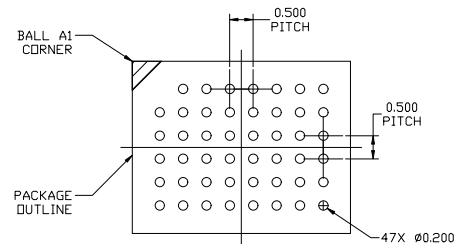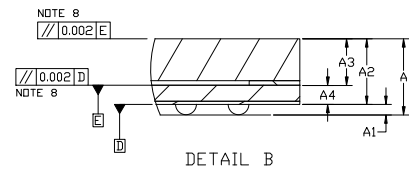**ODCSP47 4.67x3.68x0.62, 0.50P**
CASE 570AW
ISSUE A

DATE 11 DEC 2023

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2018.
2. CONTROLLING DIMENSION: MILLIMETERS [mm].
3. SOLDER BALL DIAMETER IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DATUM C, THE SEATING PLANE IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. GLASS: 0.400 THICKNESS; REFRACTIVE INDEX = 1.52.
7. AIR GAP BETWEEN GLASS AND PIXEL ARRAY: 0.043 THICKNESS.
8. PARALLELISM APPLIES ONLY TO THE ACTIVE ARRAY.
9. MAXIMUM ROTATION OF ACTIVE ARRAY RELATIVE TO DATUMS A AND B IS ±0.1°.
10. REFER TO THE DEVICE DATA SHEET FOR TOTAL PIXEL ARRAY DEFINITIONS.
11. PACKAGE CENTER (X, Y) = (0.000, 0.000).
12. OPTICAL CENTER RELATIVE TO PACKAGE CENTER (X, Y) = (0.034, −0.005).
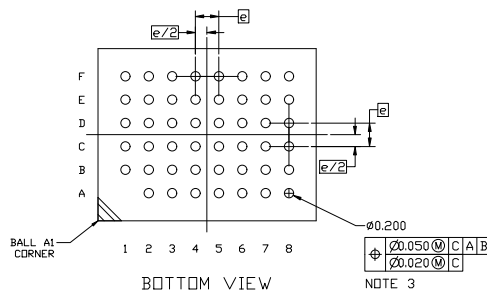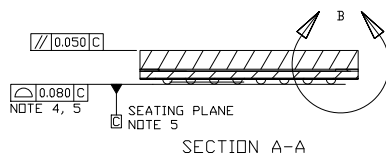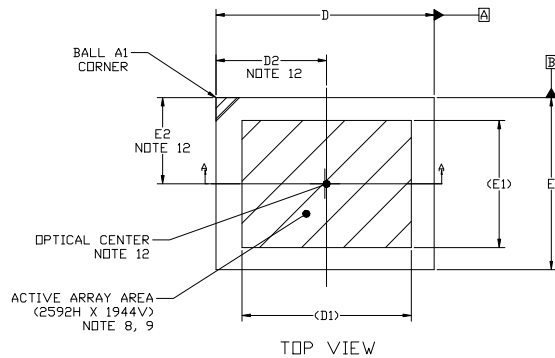
DIM	MILLIMETERS		
	MIN	NOM	MAX
A	---	---	0.781
A1	0.070	0.100	0.130
A2	0.588	0.625	0.662
A3	0.426	0.443	0.460
A4	0.162	0.182	0.202
b	0.180	0.200	0.220
D	4.648	4.673	4.698
D1	3.629 (REF)		
D2	2.346	2.371	2.396
E	3.660	3.685	3.710
E1	2.722 (REF)		
E2	1.823	1.848	1.873
e	0.500 BSC		

BALL A1 CORNER
D
A
D2 NOTE 12
B
E2 NOTE 12
(E1)
E
OPTICAL CENTER NOTE 12
ACTIVE ARRAY AREA (2592H X 1944V) NOTE 8, 9
(D1)
TOP VIEW

// 0.050 C
⌒ 0.080 C
NOTE 4, 5
SEATING PLANE
C NOTE 5
SECTION A-A

e/2
e
F E D C B A
e
e/2
1 2 3 4 5 6 7 8
Ø0.200
⊕ Ø0.050 Ⓜ C A B
⊕ Ø0.020 Ⓜ C
NOTE 3
BALL A1 CORNER
BOTTOM VIEW

NOTE 8
// 0.002 E
// 0.002 D
NOTE 8
A3 A2 A
A4
A1
E
D
DETAIL B

0.500 PITCH
BALL A1 CORNER
0.500 PITCH
PACKAGE OUTLINE
47X Ø0.200
RECOMMENDED MOUNTING FOOTPRINT

*FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

DOCUMENT NUMBER:	98AON52121H	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.	
DESCRIPTION:	ODCSP47 4.67x3.68x0.62, 0.50P		PAGE 1 OF 1